

## Silicone Thermal Fiberglass / XK-F60

### Introduction

Unlike traditional low thermal conductivity fiberglass with ceramic powder filler, XK-F series is a composite of high performance ceramic filler and 30um fiberglass, achieving high thermal conductivity on flat surface with low pressure. Recommended using for TO220/TO3P where insulation is needed.

### Features

Elastomeric compound coated on both sides  
No oil bleed, long term stability  
Electrical insulating

### Applications

Power supplies  
Automotive electronics  
Motor controls  
Power semiconductors



	unit	XK-F60	Method
Reinforcement Carrier		Fiberglass	visual
Color		White	
Thickness	mm	0.2~0.38	ASTM D374
Specific Gravity	g/cm <sup>3</sup>	2.9	ASTM D792
Hardness	Shore A	85	ASTM D2240
Thermal impedance	°Cin <sup>2</sup> /W	0.16	ASTM D5470
Thermal Conductivity	W/mK	5.8	HOT DISK
Volume Resistivity	Ωcm	>10 <sup>13</sup>	ASTM D257
Breakdown Voltage	KV	>3.5	ASTM D149
Dielectric Constant	1	3.2	ASTM D150
Application temperature	°C	-50~220	
Tensile strength	psi	>300	ASTM D149
Elongation	%	<10	ASTM D149
Siloxane Volatiles D4~D20	%	<0.01	GC-FID
Flammability	UL94	V-0	UL94